

ABSTRACT OF THE DISCLOSURE

An integrated circuit package comprising a substrate having terminal pads arranged in at least one row along a perimeter of a surface of the substrate, vias connecting the terminal pads directly to connectors on an opposite side of the substrate, a semiconductor chip mounted on the substrate, inside the perimeter, the chip having bond pads located on a surface of the chip, and a plurality of insulated bond wires, each of the bond wires extending from a bond pad on the chip to a terminal pad on the substrate, the substrate being sized and shaped to provide a sufficient number of rows of terminal pads and associated vias so that horizontal traces through the substrate are not required.